ABSTRUCT OF THE DISCLOSURE

A method of mounting a semiconductor laser component capable of preventing deterioration of laser characteristics and destruction of the semiconductor laser component due to residual stresses as well as preventing decrease of a lifetime due to increase in temperature of the semiconductor laser component. The method of mounting a semiconductor laser device includes a step of pressure bonding a semiconductor laser component on a submount by a collet while a bonding member is heated until fused or melted on a submount by heating a table on which the submount is placed. For example, the table and the collet can be heated to a temperature higher than a fusing point of the bonding member so as to reduce the heat transfer to the collet, and then heating of the table and the collet is terminated while maintaining the pressure bonding state.